

UC1856 UC2856 UC3856

Improved Current Mode PWM Controller

FEATURES

- · Pin-for-Pin Compatible With the UC3846
- 65ns Typical Delay From Shutdown to Outputs, and 50ns Typical Delay From Sync to Outputs
- Improved Current Sense Amplifier With Reduced Noise Sensitivity
- Differential Current Sense with 3V Common Mode Range
- Trimmed Oscillator Discharge Current for Accurate Deadband Control
- Accurate 1V Shutdown Threshold
- High Current Dual Totem Pole Outputs (1.5A peak)
- TTL Compatible Oscillator SYNC Pin Thresholds
- 4kV ESD Protection

DESCRIPTION

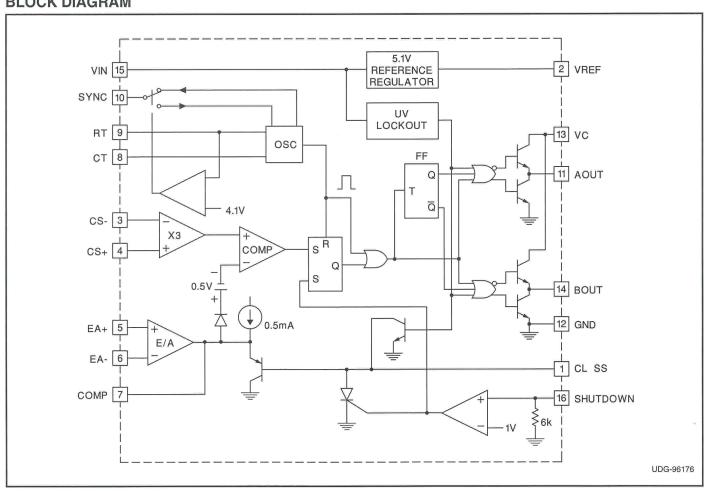
The UC3856 is a high performance version of the popular UC3846 series of current mode controllers, and is intended for both design upgrades and new applications where speed and accuracy are important. All input to output delays have been minimized, and the current sense output is slew rate limited to reduce noise sensitivity. Fast 1.5A peak output stages have been added to allow rapid switching of power FETs.

A low impedance TTL compatible sync output has been implemented with a tri-state function when used as a sync input.

Internal chip grounding has been improved to minimize internal "noise" caused when driving large capacitive loads. This, in conjunction with the improved differential current sense amplifier results in enhanced noise immunity.

Other features include a trimmed oscillator current (8%) for accurate frequency and dead time control; a 1V, 5% shutdown threshold; and 4kV minimum ESD protection on all pins.

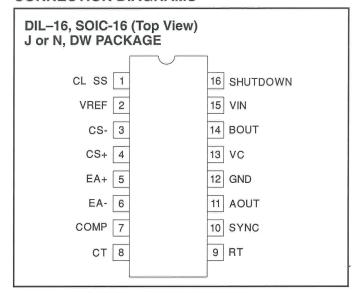
BLOCK DIAGRAM

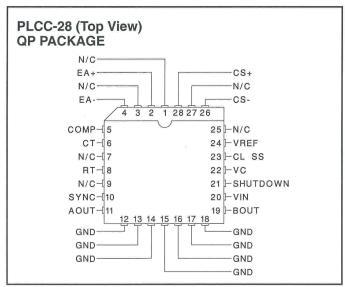


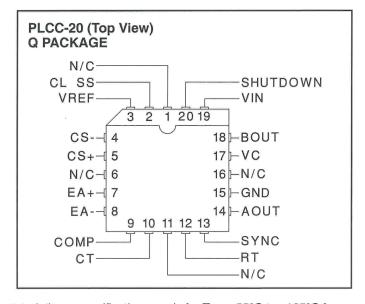
ABSOLUTE MAXIMUM RATINGS

Supply Voltage	40V
Collector Supply Voltage +	40V
Output Current, Source or Sink	
DC).5A
Pulse (0.5μs)	
Error Amp Inputs	
Shutdown Input	
Current Sense Inputs0.3V to	
SYNC Output Current±10	
Error Amplifier Output Current5	5mA
Soft Start Sink Current	
Oscillator Charging Current	
Power Dissipation at T _A = 25°C (Note 2)	
Power Dissipation at T _C = 25°C (Note 2)2000	mW
Junction Temperature	0°C
Storage Temperature Range65°C to +15	0°C
Lead Temperature (Soldering, 10 sec.) +30	0°C
All voltages are with respect to Ground. Currents are positive	ve
into, negative out of the specified terminal. Consult packagi	ng
section of databook for thermal limitations and consideration	ns
of package.	

CONNECTION DIAGRAMS







ELECTRICAL CHARACTERISTICS: Unless otherwise stated, these specifications apply for $T_A = -55^{\circ}$ C to $+125^{\circ}$ C for UC1856; -40° C to $+85^{\circ}$ C for the UC2856; and 0° C to $+70^{\circ}$ C for the UC3856, VIN = 15V, RT = 10k, CT = 1nF, $T_A = T_J$.

		UC.	1856/UC	2856	UC3856			
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Reference Section								
Output Voltage	$T_J = 25^{\circ}C, I_O = 1mA$	5.05	5.10	5.15	5.00	5.10	5.20	V
Line Regulation	VIN = 8V to 40V			20			20	mV
Load Regulation	$I_O = -1 \text{mA} \text{ to } -10 \text{mA}$			15			15	mV
Total Output Variation	Line, Load, and Temperature	5.00		5.20	4.95		5.25	V
Output Noise Voltage	10Hz < f < 10kHz, T _J = 25°C		50			50		μV
Long Term Stability	T _J = 125°C, 1000 Hrs (Note 2)		5	25		5	25	mV
Short Circuit Current	VREF = 0V	-25	-45	-65	-25	-45	-65	mA -
Oscillator Section								
Initial Accuracy	T _J = 25°C	180	200	220	180	200	220	kHz
	Over Operating Range	170		230	170		230	kHz

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		UC	1856/UC	2856		UC3856	6	
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Oscillator Section (cont.)		A-SERIA		10-2-03 NO. N	MATERIAL		1000	
Voltage Stability	VIN = 8V to 40V			2			2	%
Discharge Current	T _J = 25°C, V _{CT} = 2V	7.5	8.0	8.8	7.5	8.0	8.8	mA
	V _{CT} = 2V	6.7	8.0	8.8	6.7	8.0	8.8	mA
Sync Output High Level	$I_O = -1 \text{mA}$	2.4	3.6		2.4	3.6		V
Sync Output Low Level	I _O = +1 mA		0.2	0.4		0.2	0.4	V
Sync Input High Level	CT = 0V, RT = VREF	2.0	1.5		2.0	1.5		V
Sync Input Low Level	CT = 0V, RT = VREF		1.5	0.8		1.5	0.8	V
Sync Input Current	CT = 0V, RT = VREF V _{SYNC} = 5V		1	10		1	10	μА
Sync Delay to Outputs	CT = 0V, RT = VREF V _{SYNC} = 0.8V to 2V		50	100		50	100	ns
Error Amplifier Section							1.	
Input Offset Voltage	V _{CM} = 2V			5			10	mV
Input Bias Current				-1			-1	μА
Input Offset Current				500			500	nA
Common Mode Range	VIN = 8V to 40V	0		VIN-2	0		VIN-2	٧
Open Loop Gain	V _O = 1.2V to 3V	80	100		80	100		dB
Unity Gain Bandwidth	T _J = 25°C	1	1.5		1	1.5		MHz
CMRR	V _{CM} = 0V to 38V, VIN = 40V	75	100		75	100		dB
PSRR	VIN = 8V to 40V	80	100		80	100		dB
Output Sink Current	$V_{ID} = -15 \text{mV}, V_{COMP} = 1.2 \text{V}$		10		5	10		mA
Output Source Current	V _{ID} = 15mV, V _{COMP} = 2.5V	5 -0.4	-0.5		-0.4	-0.5		mA
Output High Level	V _{ID} = 50mV, R _L (COMP) = 15k	4.3	4.6	4.9	4.3	4.6	4.9	V
Output Low Level	$V_{ID} = -50 \text{mV}, R_L \text{ (COMP)} = 15 \text{k}$		0.7	1		0.7	1	V
Current Sense Amplifier Section					-			
Amplifier Gain	V _{CS} – = 0V, CL SS Open (Notes 3,4)	2.5	2.75	3.0	2.5	2.75	3.0	V/V
Maximum Differential Input Signal (Vcs+ - Vcs-)	CL SS Open (Note 3) R _L (COMP) = 15k	1.1	1.2		1.1	1.2		V
Input Offset Voltage	V _{CL SS} = 0.5VCOMP Open (Note 3)		5	35		5	35	mV
CMRR	V _{CM} = 0V to 3V	60			60			dB
PSRR	VIN = 8V to 40V	60			60			dB
Input Bias Current	V _{CL SS} = 0.5V, COMP Open (Note 3)	÷1		1	-1		1	μА
Input Offset Current	V _{CL SS} = 0.5V, COMP Open (Note 3)	-1		1	-1		1	μА
Input Common Mode Range		0		3	0		3	٧
Delay to Outputs	V _{EA} + = VREF, EA- = 0V CS+ - CS- = 0V to 1.5V		120	250		120	250	ns
Current Limit Adjust Section								
Current Limit Offset	V_{CS} -= 0V V_{CS} += 0V, COMP = Open (Note 3)	0.43	0.5	0.57	0.43	0.5	0.57	٧
Input Bias Current	V _{EA} + = VREF, V _{EA} - = 0V		-10	-30		-10	-30	μА
Shutdown Terminal Section								
Threshold Voltage		0.95	1.00	1.05	0.95	1.00	1.05	V
Input Voltage Range		0		5	0		5	٧

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		UC.	1856/UC	2856		UC3856	i	
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Shutdown Terminal Section (cont.	.)							
Minimum Latching Current (IcL ss)	(Note 5)	3	1.5		3	1.5		mA
Maximum Non-Latching Current (IcLss)	(Note 6)		1.5	0.8		1.5	0.8	mA
Delay to Outputs	$V_{SHUTDOWN} = 0$ to 1.3V		65	110		65	110	ns
Output Section								
Collector-Emitter Voltage		40			40			V
Off-State Bias Current	VC = 40V			250			250	μА
Output Low Level	I _{OUT} = 20mA		0.1	0.5		0.1	0.5	V
	$I_{OUT} = 200 \text{mA}$		0.5	2.6		0.5	2.6	V
Output High Level	$I_{OUT} = -20mA$	12.5	13.2		12.5	13.2		V .
	$I_{OUT} = -200 \text{mA}$	12	13.1		12	13.1		V
Rise Time	C1 = 1nF		40	80		40	80	ns
Fall Time	C1 = 1nF		40	80		40	80	ns
UVLO Low Saturation	VIN = 0V, I _{OUT} = 20mA		0.8	1.5		0.8	1.5	V
PWM Section								
Maximum Duty Cycle		45	47	50	45	47	50	%
Minimum Duty Cycle				0			0	%
Undervoltage Lockout Section							,	
Startup Threshold		h.	7.7	8.0		7.7	8.0	V
Threshold Hysterisis			0.7			0.7		V
Total Standby Current							,	
Supply Current			18	23		18	23	mA

Note 1: All voltages are with respect to GND. Currents are positive into, negative out of the specified terminal.

Note 2: This parameter, although guaranteed over the recommended operating conditions is not 100% tested in production.

Note 3: Parameter measured at trip point of latch with V_{EA} + = VREF, V_{EA} - = 0V.

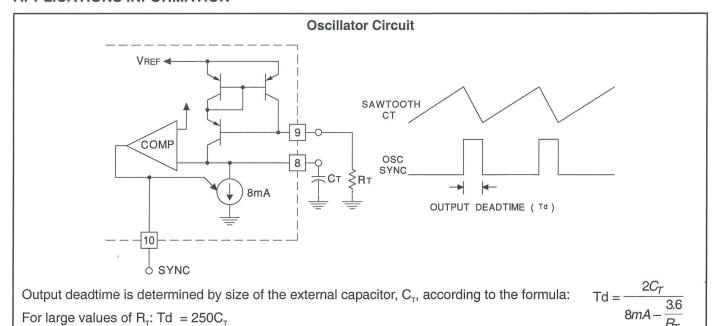
Note 4: Amplifier gain defined as:

$$G = \frac{\Delta V_{COMP}}{\Delta V_{CS}}; \quad \Delta V_{CS} = 0VTO1.0V$$

Note 5: Current into CL SS guaranteed to latch circuit into shutdown state.

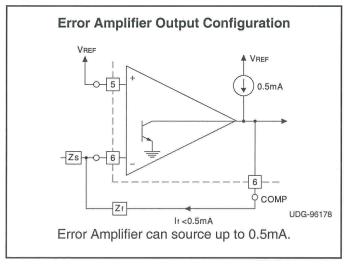
Note 6: Current into CL SS guaranteed not to latch circuit into shutdown state.

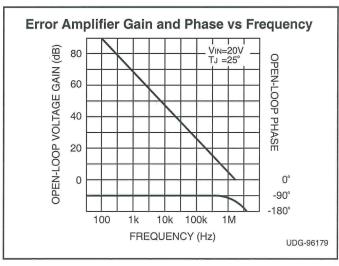
APPLICATIONS INFORMATION

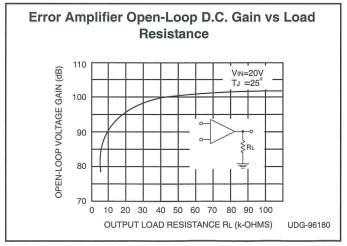


Oscillator frequency is approximated by the formula: $f_T = \frac{2}{R_T C_T}$

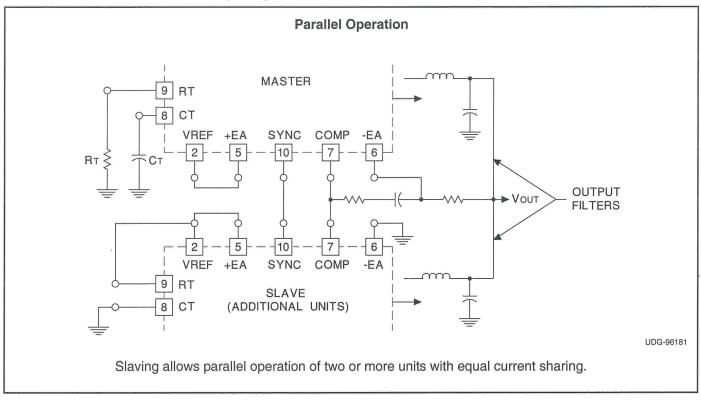
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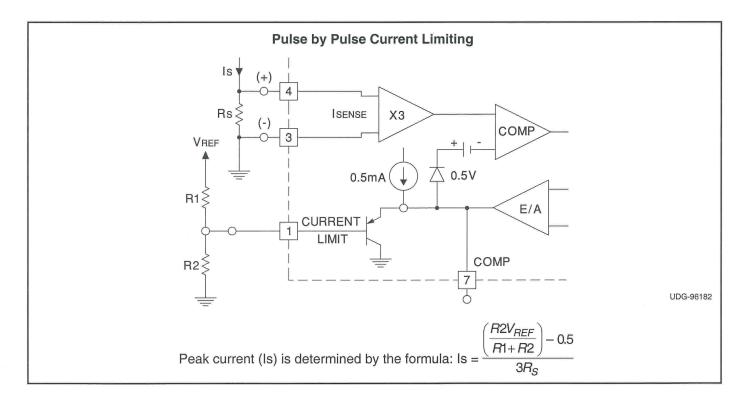




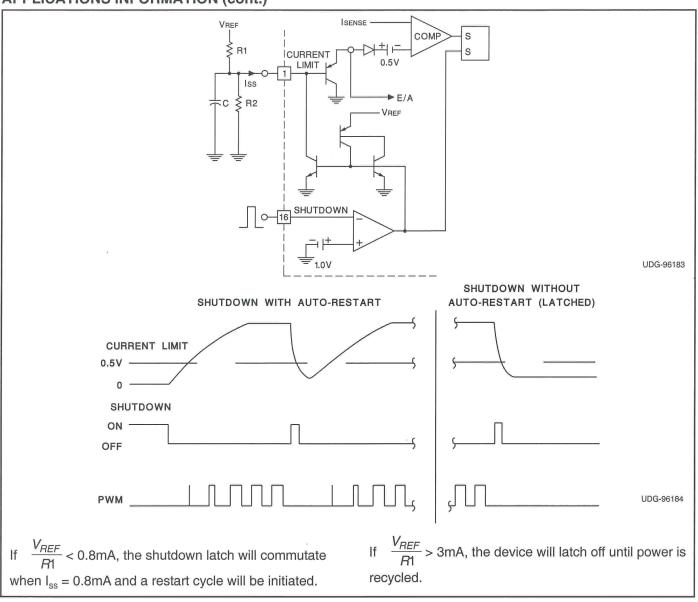


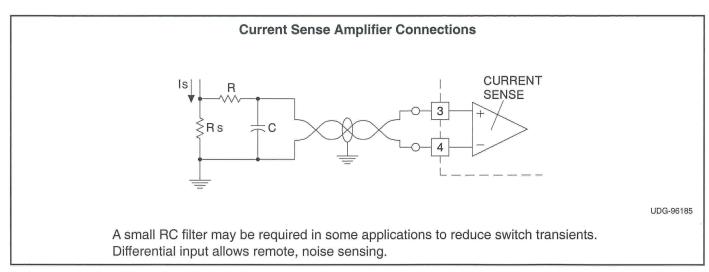
APPLICATIONS INFORMATION (cont.)



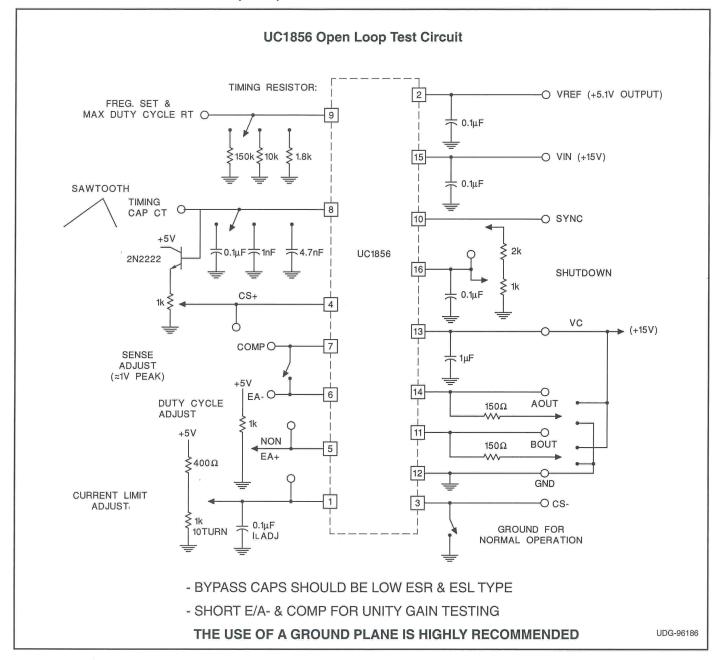


APPLICATIONS INFORMATION (cont.)





APPLICATIONS INFORMATION (cont.)



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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-9453001M2A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9453001M2A UC1856L20/ 883B
5962-9453001MEA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9453001ME A UC1856J/883B
UC1856J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	UC1856J
UC1856J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	UC1856J
UC1856J883B	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9453001ME A UC1856J/883B
UC1856J883B.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9453001ME A UC1856J/883B
UC1856L20	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	UC1856L20
UC1856L20.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	UC1856L20
UC1856L20883B	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9453001M2A UC1856L20/ 883B
UC1856L20883B.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9453001M2A UC1856L20/ 883B
UC2856DW	Obsolete	Production	SOIC (DW) 16	-	-	Call TI	Call TI	-40 to 85	UC2856DW
UC2856DWTR	Obsolete	Production	SOIC (DW) 16	-	-	Call TI	Call TI	-40 to 85	UC2856DW
UC2856J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-40 to 85	UC2856J
UC2856J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-40 to 85	UC2856J
UC2856N	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	UC2856N
UC2856N.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	UC2856N
UC3856DW	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3856DW
UC3856DW.A	Active	Production	SOIC (DW) 16	40 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3856DW

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Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
UC3856DWTR	Active	Production	SOIC (DW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3856DW
UC3856DWTR.A	Active	Production	SOIC (DW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3856DW
UC3856N	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	UC3856N
UC3856N.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	UC3856N
UC3856NG4	Active	Production	PDIP (N) 16	25 I TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	UC3856N

⁽¹⁾ Status: For more details on status, see our product life cycle.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF UC1856, UC2856, UC2856M, UC3856:

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.



PACKAGE OPTION ADDENDUM

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● Catalog : UC3856, UC2856

• Automotive : UC2856-Q1, UC2856-Q1

• Military : UC2856M, UC1856

• Space : UC1856-SP

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

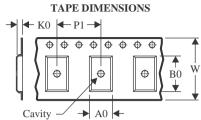
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

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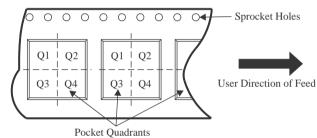
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

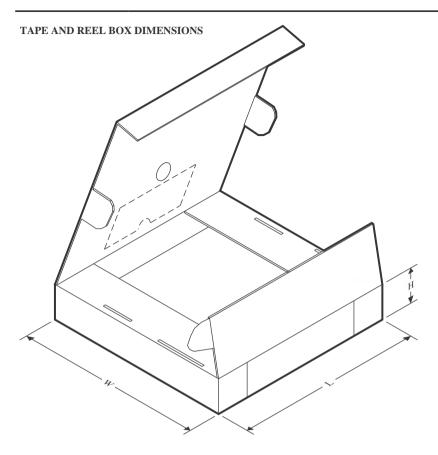


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC3856DWTR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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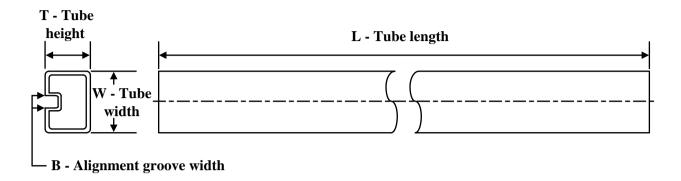
*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	UC3856DWTR	SOIC	DW	16	2000	353.0	353.0	32.0

PACKAGE MATERIALS INFORMATION

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TUBE



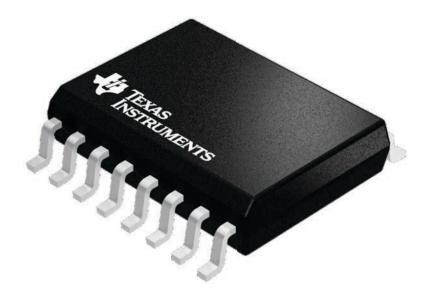
*All dimensions are nominal

All difficusions are nominal				•				
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9453001M2A	FK	LCCC	20	55	506.98	12.06	2030	NA
UC1856L20	FK	LCCC	20	55	506.98	12.06	2030	NA
UC1856L20.A	FK	LCCC	20	55	506.98	12.06	2030	NA
UC1856L20883B	FK	LCCC	20	55	506.98	12.06	2030	NA
UC1856L20883B.A	FK	LCCC	20	55	506.98	12.06	2030	NA
UC2856N	N	PDIP	16	25	506	13.97	11230	4.32
UC2856N.A	N	PDIP	16	25	506	13.97	11230	4.32
UC3856DW	DW	SOIC	16	40	507	12.83	5080	6.6
UC3856DW.A	DW	SOIC	16	40	507	12.83	5080	6.6
UC3856N	N	PDIP	16	25	506	13.97	11230	4.32
UC3856N.A	N	PDIP	16	25	506	13.97	11230	4.32
UC3856NG4	N	PDIP	16	25	506	13.97	11230	4.32

7.5 x 10.3, 1.27 mm pitch

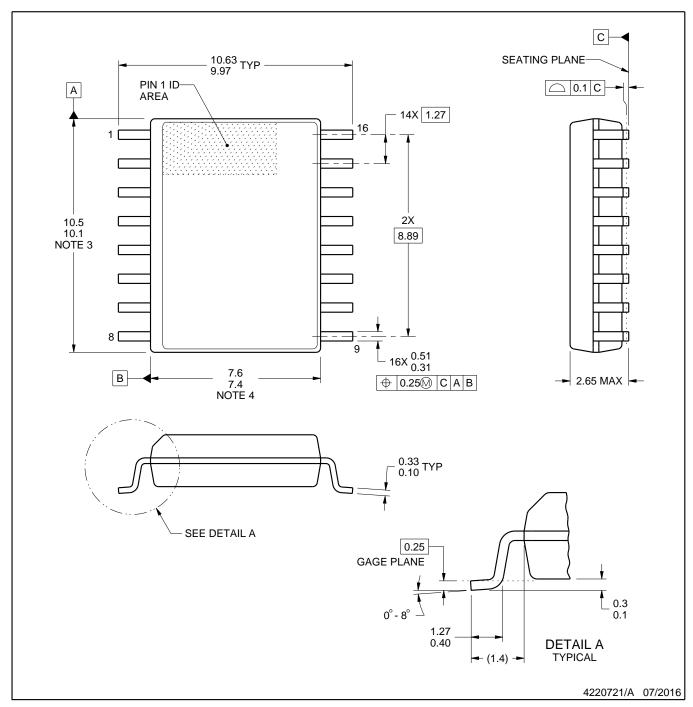
SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





SOIC



NOTES:

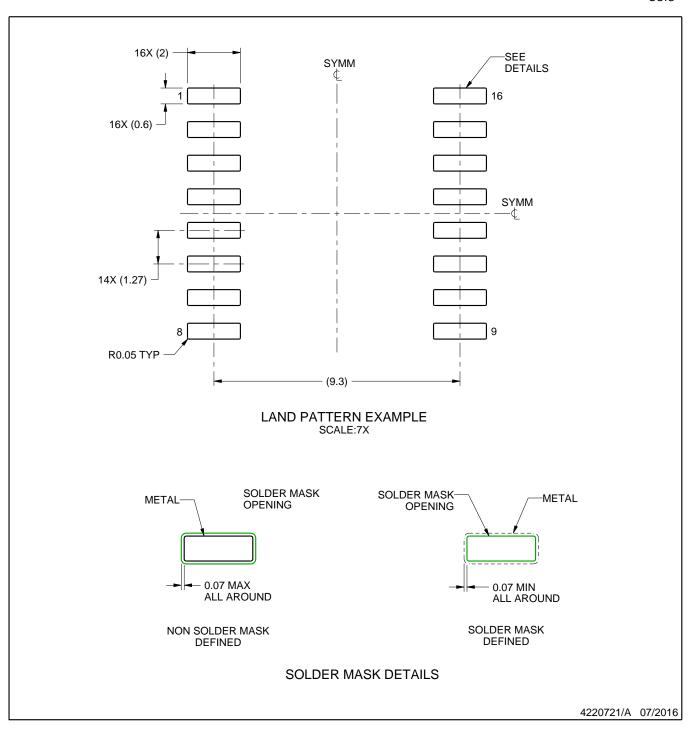
- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
- 5. Reference JEDEC registration MS-013.



SOIC



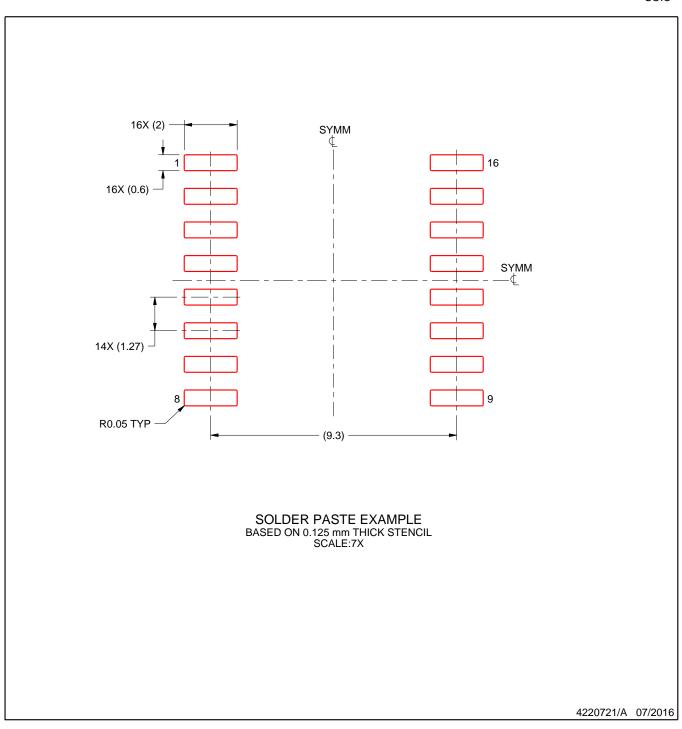
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

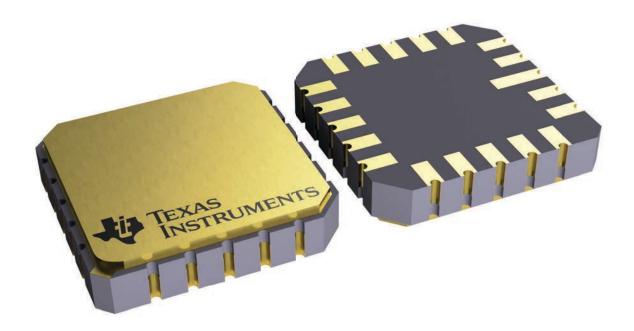
- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



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14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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